

PART INFORMATION

Mfg Item Number	MC68LC060RC75
Mfg Item Name	PGA 206

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-06-22
Response Document ID	0835K00058D004A1.6
Contact Name	Freescale Semiconductor Inc
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Representative Title	EPP Customer Response
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DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	7c-I

MANUFACTURING

Mfg Item Number	MC68LC060RC75
Mfg Item Name	PGA 206
Version	ALL
Weight	25.846950
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Header Assembly	23.749						g				
Header Assembly		Metals	Aluminum Oxides (Al2O3)	1344-28-1		18.30936279	g	770953	77.0953	708389	70.8389
Header Assembly		Solvents, additives, and other materials	Calcium monoxide	1305-78-8		0.12361355	g	5205	0.5205	4782	0.4782
Header Assembly		Metals	Chromium, metal	7440-47-3		0.78174583	g	32917	3.2917	30245	3.0245
Header Assembly		Metals	Cobalt, metal	7440-48-4		0.23276395	g	9801	0.9801	9005	0.9005
Header Assembly		Metals	Copper, metal	7440-50-8		0.02237156	g	942	0.0942	865	0.0865
Header Assembly		Metals	Gold, metal	7440-57-5		0.07533183	g	3172	0.3172	2914	0.2914
Header Assembly		Metals	Iron, metal	7439-89-6		0.71548612	g	30127	3.0127	27681	2.7681
Header Assembly		Metals	Magnesium, metal	7439-95-4		0.100957	g	4251	0.4251	3905	0.3905
Header Assembly		Metals	Molybdenum, metal	7439-98-7		0.00436982	g	184	0.0184	169	0.0169
Header Assembly		Nickel (external applications only)	Nickel	7440-02-0		0.47080018	g	19824	1.9824	18214	1.8214
Header Assembly		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.71273124	g	30011	3.0011	27575	2.7575
Header Assembly		Metals	Silver, metal	7440-22-4		0.12672466	g	5336	0.5336	4902	0.4902
Header Assembly		Metals	Titanium (IV) Oxide	13463-67-7		0.20272146	g	8536	0.8536	7843	0.7843
Header Assembly		Metals	Tungsten, metal	7440-33-7		1.87002001	g	78741	7.8741	72349	7.2349
Cap/Cover	1.8488						g				
Cap/Cover		Metals	Cobalt, metal	7440-48-4		0.27732	g	150000	15	10729	1.0729
Cap/Cover		Metals	Gold, metal	7440-57-5		0.073952	g	40000	4	2861	0.2861
Cap/Cover		Metals	Iron, metal	7439-89-6		0.9244	g	500000	50	35764	3.5764
Cap/Cover		Nickel (external applications only)	Nickel	7440-02-0		0.55464	g	300000	30	21458	2.1458
Cap/Cover		Metals	Tin, metal	7440-31-5		0.018488	g	10000	1	715	0.0715
Epoxy Die Attach	0.0784				7c-1		g				
Epoxy Die Attach		Lead/Lead Compounds	Lead (II) oxide	1317-36-8		0.00161982	g	20661	2.0661	62	0.0062
Epoxy Die Attach		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.00647937	g	82645	8.2645	250	0.025
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.06479345	g	826447	82.6447	2506	0.2506
Epoxy Die Attach		Metals	Silver (I) oxide	20667-12-3		0.00323964	g	41322	4.1322	125	0.0125
Epoxy Die Attach		Metals	Tellurium in Glass frnt	7446-07-3		0.0006479	g	8264	0.8264	25	0.0025
Epoxy Die Attach		Metals	Vanadium (V) oxide	1314-62-1		0.00161982	g	20661	2.0661	62	0.0062
Bonding Wire, Aluminum	0.001						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.001	g	1000000	100	38	0.0038
Silicon Semiconductor Die	0.16975						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.003395	g	20000	2	131	0.0131
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.166355	g	980000	98	6436	0.6436

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC68LC060RC75_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC68LC060RC75_IPC1752A.xml